

What is claimed is:

1. A flexible printed circuit board comprising a base film; a base film side adhesive layer provided on the base film; a metal foil layer on which pattern circuit is formed, provided on the base film side adhesive layer; and a cover layer side adhesive layer provided on the metal foil layer,

wherein at least one of the base film side adhesive and the cover layer side adhesive layer has a higher glass transition temperature than the working environment temperature of the flexible printed circuit board.

2. A flexible printed circuit board according to claim 1, wherein the glass transition temperature is 60°C or higher.

3. A flexible printed circuit board according to claim 1, wherein the glass transition temperature is 80°C or higher.

4. A flexible printed circuit board according to claim 1, wherein at least one of the base film side adhesive layer and the cover layer side adhesive layer is made of an epoxy resin adhesive.

5. A flexible printed circuit board according to claim 1, wherein a bending life of the flexible printed circuit board is ten million times or greater per minute at 60°C.

6. A flexible printed circuit board according to claim 1, wherein per bending life of the flexible printed circuit board is between a million times and ten millions per minute at 80°C.

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10.7